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ABSTRACT

BUMP LEVELLING METHOD AND BUMP LEVELLING APPARATUS

The present invention provides a bump levelling method and a bump levelling apparatus in which the levelled height of bumps can be made constant and meet the change in thickness of an IC chip. A pressing force under which one bump (20) is deformed to a prescribed height is measured. Thus, the pressing force under which a plurality of bumps (20) can be deformed and levelled can be set. A load cell (14) detects that a prescribed pressing force is exerted on the bumps and this pressing force is maintained, so that the plurality of bumps (20) can be levelled up to the same prescribed height.

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